



PerF≝T[™]Power Transistor

FEATURES

- Excellent FOM
- Reliability meets AEC-Q101 requirements
- Wettable flank leads for enhanced AOI
- 100% UIS and Rg tested
- 175°C operating junction temperature
- RoHS Compliant
- Halogen-free

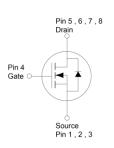
KEY PERFORMANCE PARAMETERS				
PARAMETER		VALUE	UNIT	
V_{DS}		100	V	
D (22.2.)	V _{GS} = 10V	10		
R _{DS(on)} (max)	V _{GS} = 4.5V	14	mΩ	
Q_g	V _{GS} = 4.5V	13	nC	



APPLICATIONS

- Solenoid and motor drivers
- DC-DC converters
- Load Switch
- SMPS





Note: MSL 1 (Moisture Sensitivity Level) per J-STD-020

ABSOLUTE MAXIMUM RATINGS (T _A = 25°C unless otherwise noted)					
PARAMETER		SYMBOL	LIMIT	UNIT	
Drain-Source Voltage		V_{DS}	100	V	
Gate-Source Voltage		V _G s	±20	V	
Continuous Drain Current	T _C = 25°C		72		
	T _C = 100°C	l _D	51	Α	
	T _A = 25°C		12		
Pulsed Drain Current (Note 1)		I _{DM}	288	А	
Single Pulse Avalanche Current (Note 2)		las	14.9	А	
Single Pulse Avalanche Energy (Note 2)		Eas	33.3	mJ	
Total Power Dissipation	T _C = 25°C	Б	115	14/	
	T _C = 125°C	P _D	38	W	
Operating Junction and Storage Temperature Range		T _J , T _{STG}	- 55 to +175	°C	

THERMAL PERFORMANCE				
PARAMETER	SYMBOL	LIMIT	UNIT	
Junction to Case Thermal Resistance	Rejc	1.3	°C/W	
Junction to Ambient Thermal Resistance (Note 3)	R _{OJA}	50	°C/W	

1

Notes:

- 1. Pulse Width ≤ 100µs.
- 2. L = 0.3mH, V_{GS} = 10V, R_{G} = 25 Ω , Starting T_{J} = 25 $^{\circ}$ C.
- 3. Device on a PCB FR4 with 1 in² (single layer, 2 oz thickness) copper area for drain connection.



PARAMETER	CONDITIONS	SYMBOL	MIN	TYP	MAX	UNIT
Static						
Drain-Source Breakdown Voltage	$V_{GS} = 0V$, $I_D = 1mA$	BV _{DSS}	100			V
Gate Threshold Voltage	$V_{DS} = V_{GS}, I_D = 250 \mu A$	V _{GS(TH)}	1.4	1.6	2.2	V
Gate Body Leakage	$V_{GS} = \pm 20V, V_{DS} = 0V$	I _{GSS}			±100	nA
	V _{GS} = 0V, V _{DS} = 100V				1	μA
Drain-Source Leakage Current	V _G S = 0V, V _D S = 100V T _J = 125°C	IDSS			100	
Drain-Source On-State Resistance	V _{GS} = 10V, I _D = 36A		-	7.4	10	mΩ
(Note 4)	V _{GS} = 4.5V, I _D = 36A	R _{DS(on)}		9.1	14	
Forward Transconductance (Note 4)	$V_{DS} = 10V, I_{D} = 9A$	G fs		53		S
Dynamic (Note 5)						•
Total Gate Charge	$V_{DS} = 50V, I_{D} = 12A,$ $V_{GS} = 4.5V$	Qg		13		nC
Total Gate Charge		Qg		25		
Gate-Source Charge	$V_{DS} = 50V, I_{D} = 12A,$	Q _{gs}		5.3		nC
Gate-Drain Charge	V _{GS} = 10V	Q _{gd}		3.8		
Input Capacitance		Ciss		1363		
Output Capacitance	$V_{DS} = 60V$, $V_{GS} = 0V$,	Coss	-	228		pF
Reverse Transfer Capacitance	f = 1.0MHz	Crss	-	26		
Gate Resistance	f = 1.0MHz	Rg		0.5		Ω
Switching (Note 6)						
Turn-On Delay Time		t _{d(on)}		8.6		
Turn-On Rise Time	$V_{DD} = 50V$, $R_G = 6\Omega$,	tr		24		
Turn-Off Delay Time	$I_D = 12A, V_{GS} = 10V$	t _{d(off)}		26		ns
Turn-Off Fall Time		t _f	-	52		
Source-Drain Diode						
Forward Voltage (Note 4)	I _S = 36A, V _{GS} = 0V	V _{SD}			1.1	V
Reverse Recovery Time	I _S = 12A,	t _{rr}		62		ns
Reverse Recovery Charge	di/dt = 100A/µs	Qrr		95		nC

Notes:

- 4. Pulse test: Pulse Width $\leq 300 \mu s$, duty cycle $\leq 2\%$.
- 5. Defined by design. Not subject to production test.
- 6. Switching time is essentially independent of operating temperature.

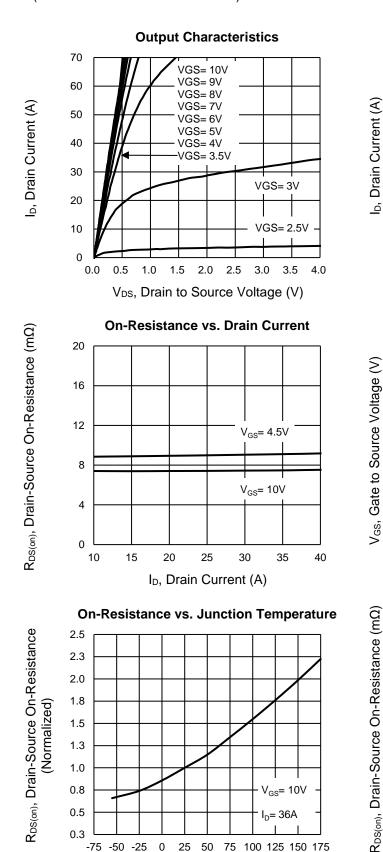
ORDERING INFORMATION

ORDERING CODE	PACKAGE	PACKING
TSM100NH10LCR RLG	PDFN56U	2,500pcs / 13" Reel



CHARACTERISTICS CURVES

 $(T_A = 25^{\circ}C \text{ unless otherwise noted})$



50

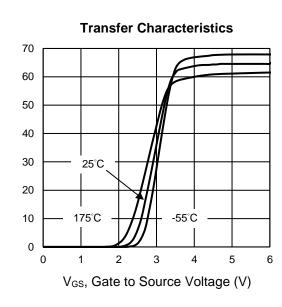
T_J, Junction Temperature (°C)

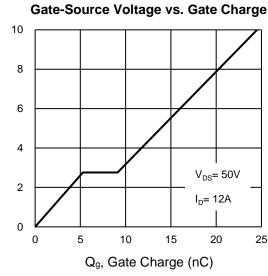
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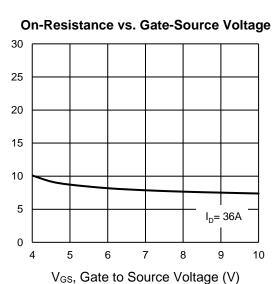
75 100 125 150 175

3

0.3









CHARACTERISTICS CURVES

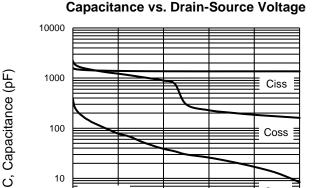
 $(T_A = 25^{\circ}C \text{ unless otherwise noted})$

 $V_{GS} = 0\dot{V}$

20

0

Normalized Effective Transient Thermal Impedance, Zeuc



BV_{DSS} vs. Junction Temperature 1.20 Drain-Source Breakdown Voltage 1.15 1.10 BV_{DSS} (Normalized) 1.05 1.00 0.95 0.90 $I_D = 1mA$ 0.85 0.80 -50 -25 0 25 50 75 100 125 150 175 T_J, Junction Temperature (°C)

Maximum Safe Operating Area, Junction-to-Case

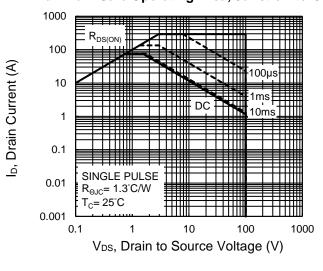
V_{DS}, Drain to Source Voltage (V)

40

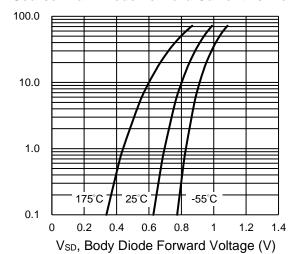
Crss

100

80

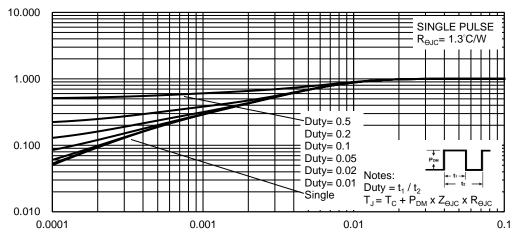


Source-Drain Diode Forward Current vs. Voltage



Normalized Thermal Transient Impedance, Junction-to-Case

ls, Reverse Drain Current (A)



t, Square Wave Pulse Duration (sec)

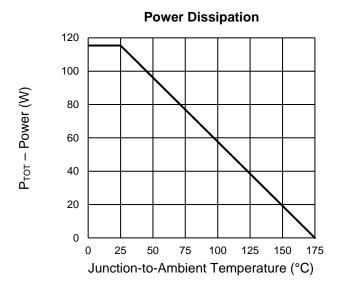
4

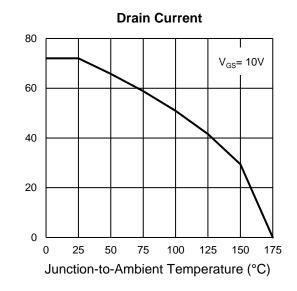


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CHARACTERISTICS CURVES

(T_A = 25°C unless otherwise noted)

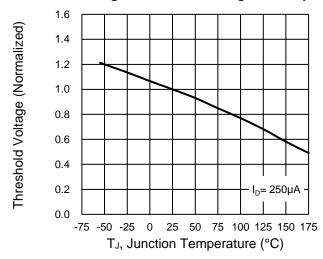




I_D-Drain Current (A)

5

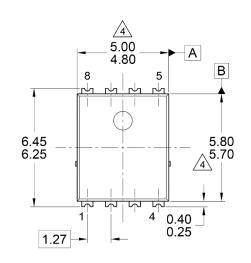
Normalized gate threshold voltage vs Temperature

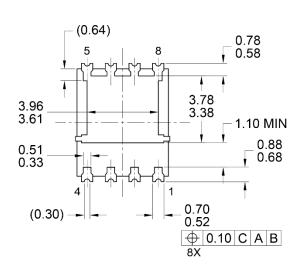


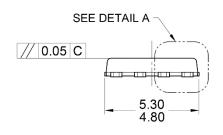


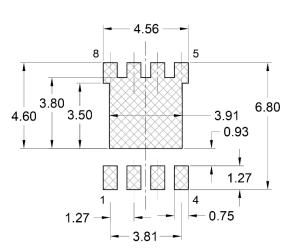
PACKAGE OUTLINE DIMENSIONS (Unit: Millimeters)

PDFN56U









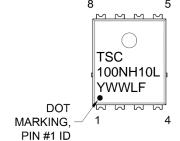
SUGGESTED PAD LAYOUT

(REFERENCE ONLY)

0.90MIN 1.10 0.90 0.30 0.20 0.05 0.00 C

SEATING PLANE

DETAIL A (SCALE 2:1)



MARKING DIAGRAM

NOTES: UNLESS OTHERWISE SPECIFIED

- 1. ALL DIMENSIONS ARE IN MILLIMETERS.
- DIMENSIONING AND TOLERANCING PER ASME Y14.5M-1994.
- 3. PACKAGE OUTLINE REFERENCE: JEITA ED-7500B, EIAJ SC-111BB.
- MOLDED PLASTIC BODY DIMENSIONS DO NOT INCLUDE MOLD FLASH, PROTRUSIONS OR GATE BURRS.
- 5. DWG NO. REF: HQ2SD07-PDFN56U-023 REV B.

100NH10L = Device marking

Y = Year code WW = Week code $(01\sim52)$ L = Lot code $(1\sim9,A\sim Z)$

F = Factory code



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